



US00D564455S

(12) **United States Design Patent**
Ng et al.

(10) **Patent No.:** **US D564,455 S**
(45) **Date of Patent:** **** Mar. 18, 2008**

(54) **CIRCUIT PACK**

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(**) Term: **14 Years**

(21) Appl. No.: **29/200,741**

(22) Filed: **Mar. 3, 2004**

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/158**

(58) **Field of Classification Search** D13/184,
D13/158; D14/240; 174/67; 361/679, 796,
361/690

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a circuit pack, as shown and described.

DESCRIPTION

FIG. 1 is an isometric view of a circuit pack with the door closed showing our design.

FIG. 2 is a front view of the circuit pack with the door closed.

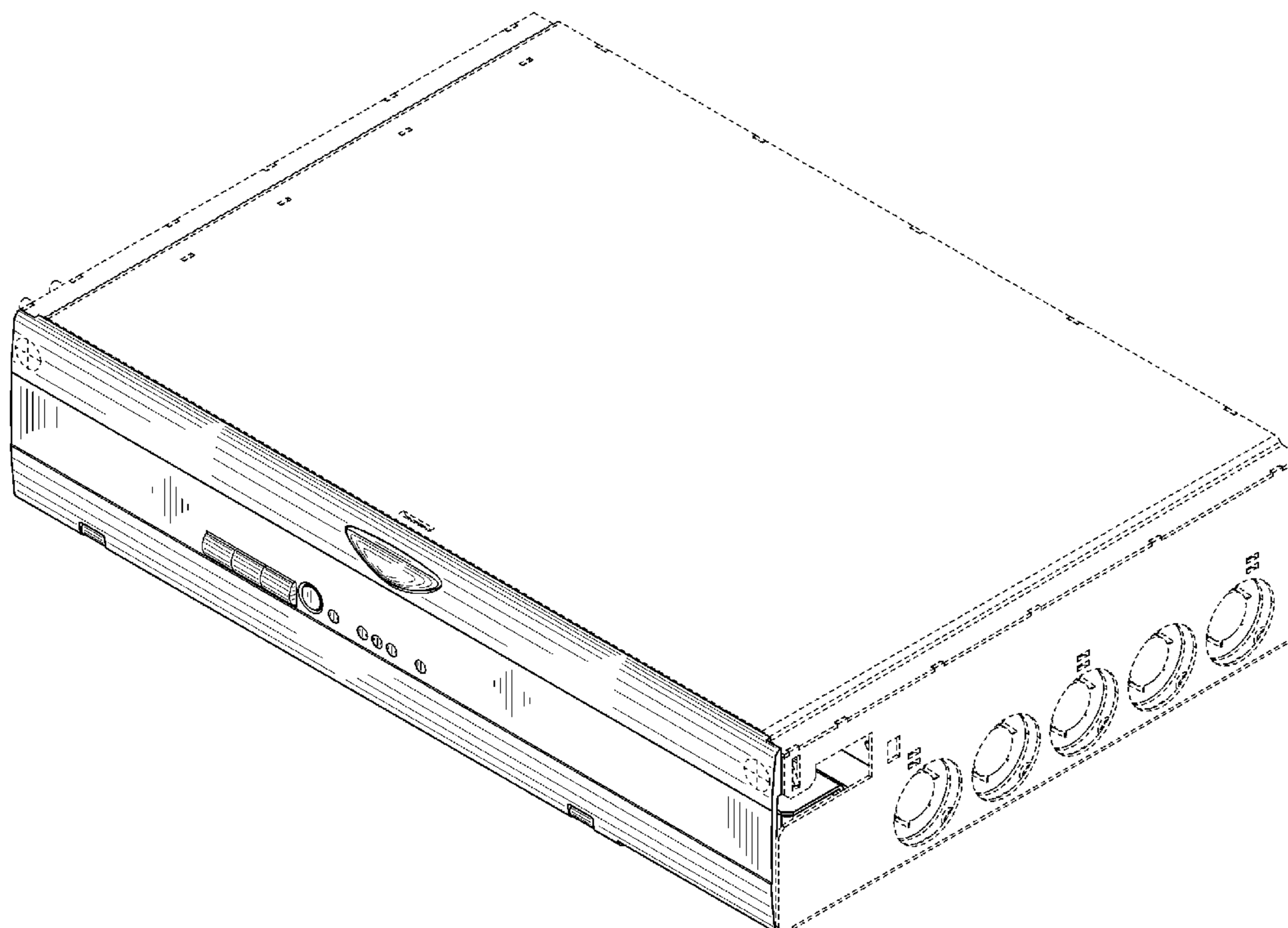
FIG. 3 is an isometric view of the circuit pack with the door open; and,

FIG. 4 is a front view of the circuit pack with the door open.

The top, bottom, and sides of the circuit pack are unornamented.

The broken lines are shown for illustrative purposes only and form no part of the claimed design.

1 Claim, 4 Drawing Sheets



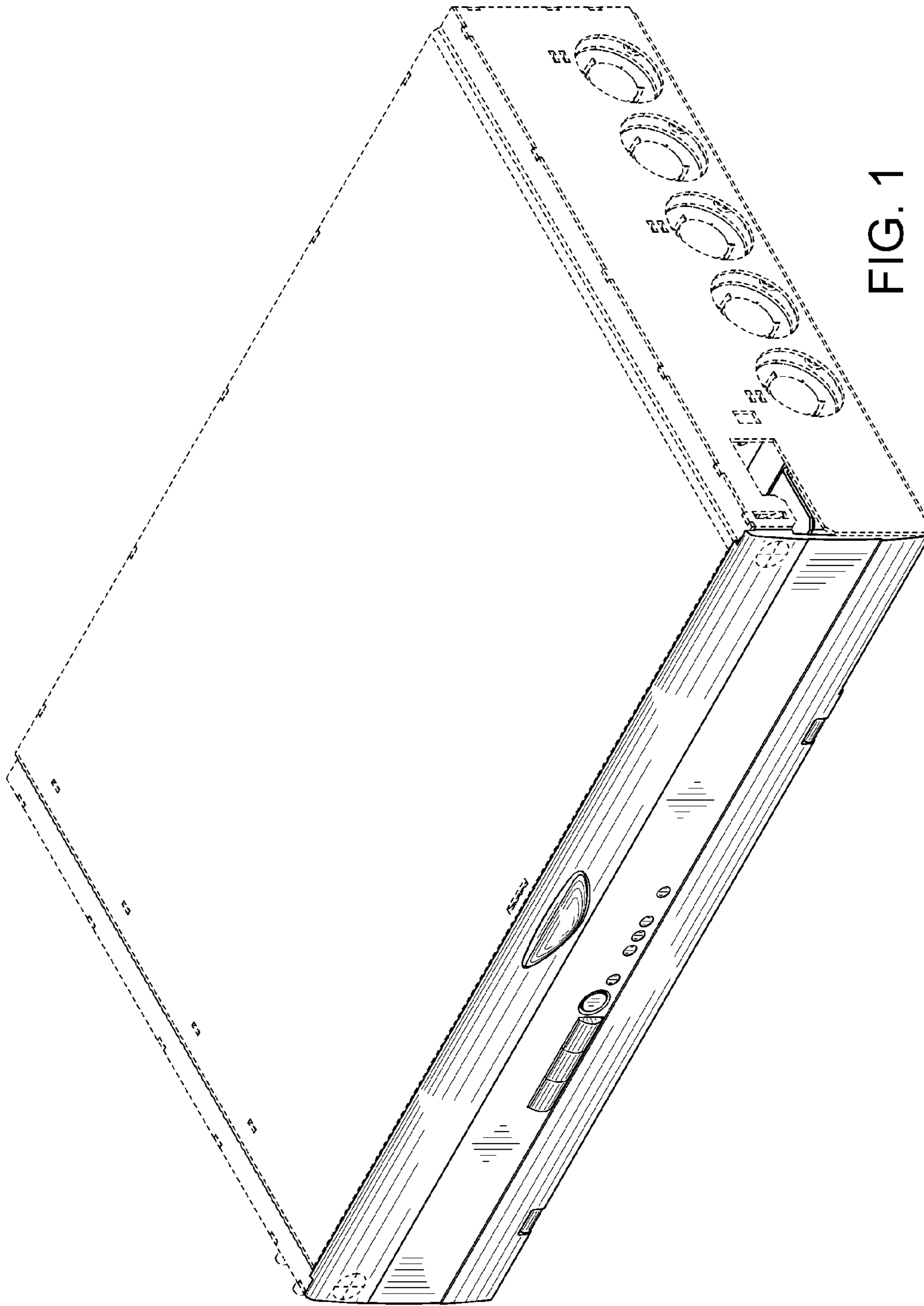


FIG. 1

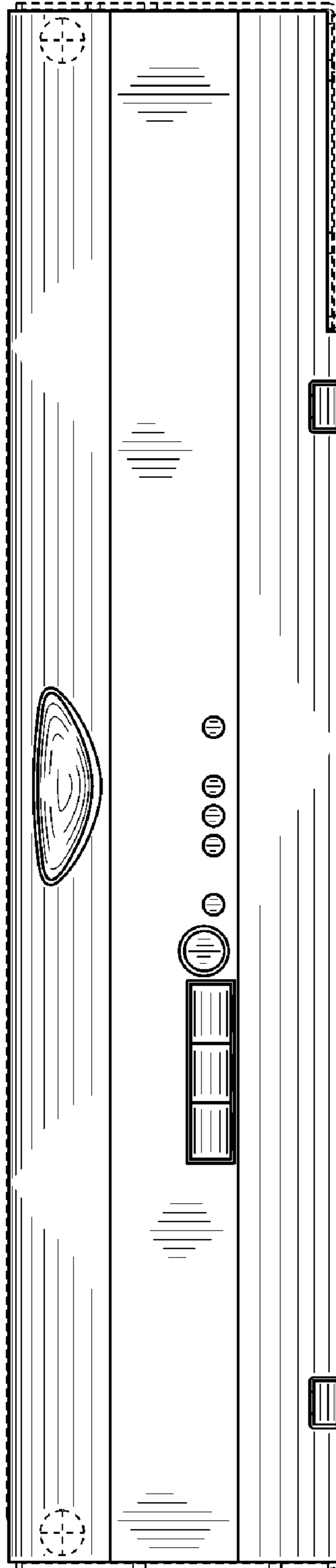


FIG. 2

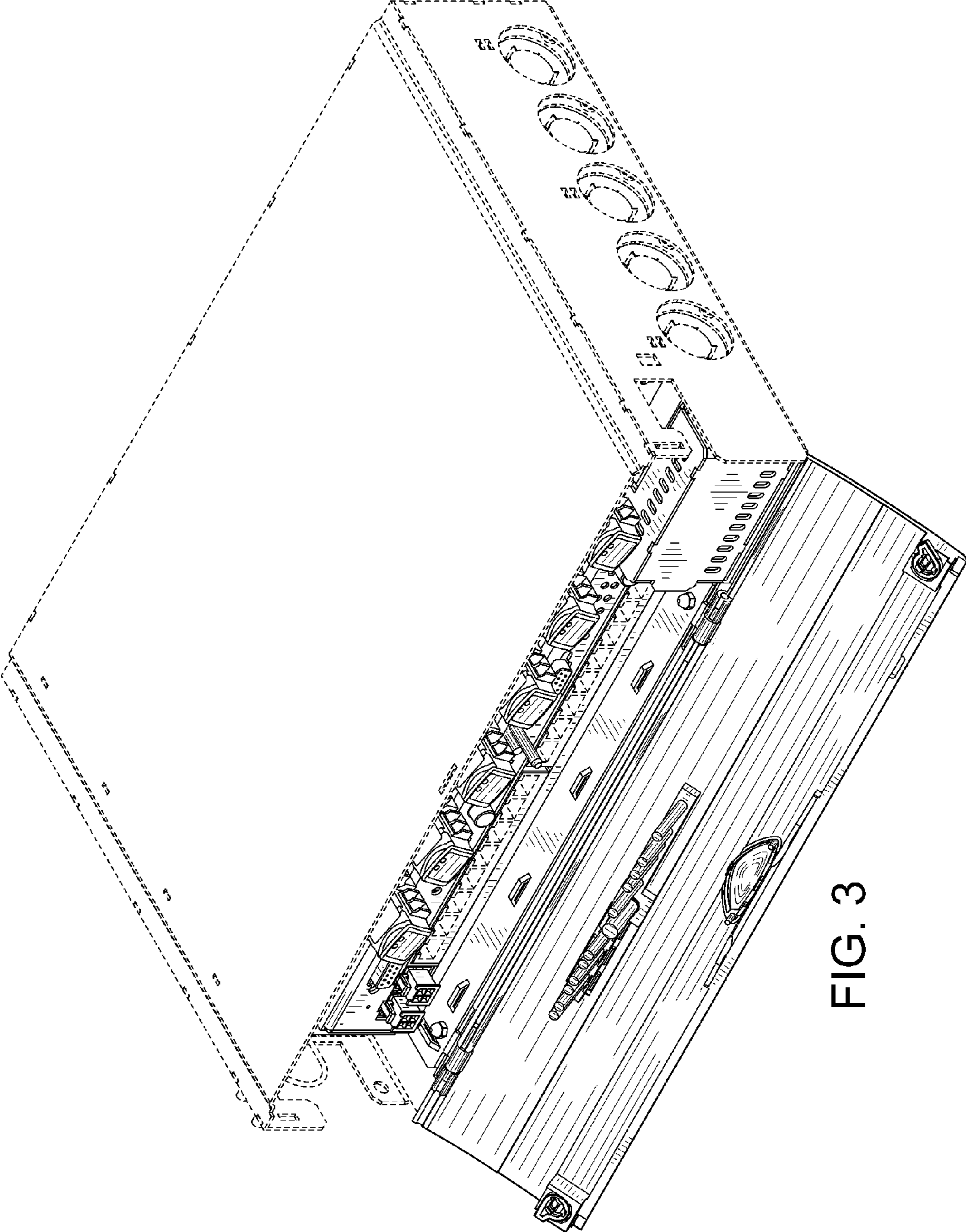


FIG. 3

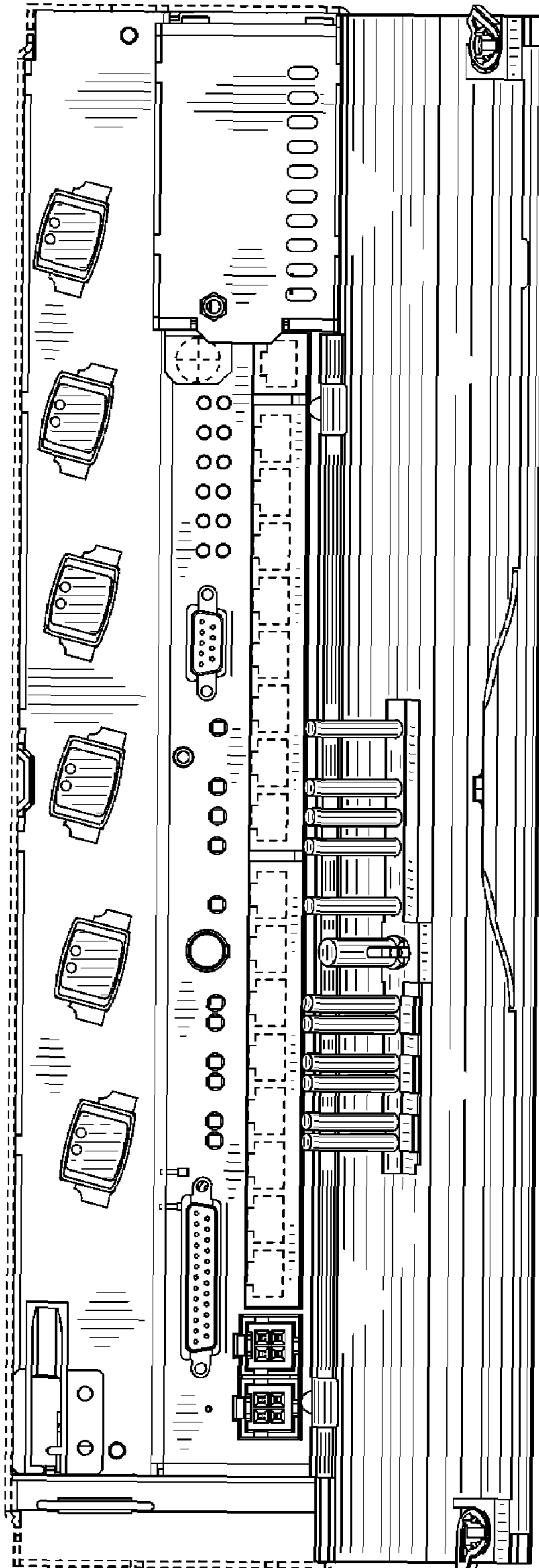


FIG. 4